

# ASIC gluing - Mask method

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An example of gluing step is shown in a photo in the next page, in the chip location, from left to right:

- 1) A "blue film" mask attached, one mask per chip, which extends up to the edges of capacitors and long enough over the bus lines so that the mask can be peeled off easily. The opening is "X"-shaped. The "blue film" is the standard one for protecting electronics components. The thickness is 90  $\mu\text{m}$ .
- 2) A conductive epoxy is applied and "scraped"
- 3) The "blue tape" mask is peeled out
- 4) A dummy chip is placed, squeezing the epoxy out till to form a smooth fillet on the side walls

In the real fabrication, 6 chips are done simultaneously.

